Conference

pcim ASIA SHENZHEN

Wednesday, August, 26, 2026 | Shenzhen World Exhibition and Convention Center, China | Conference Room 14

Morning Session

9:00 a.m. Conference Room 14B

Conference Opening & Award Ceremony

Conference Director: Leo Lorenz, ECPE, DE

9:40 a.m. Conference Room 14B

Keynote 1

Challenges and Innovations in Data Center Power Systems to Meet the AI Power Demand

Speaker:
Dehong Xu,
Zhejiang University, CN

Chairperson:
Leo Lorenz,
ECPE, DE

10:20 a.m. Tea Break

10:35 a.m. Conference Room 14B

Special Session1

Power Supply for AI Data Center

Chair's opening speech

Chairperson:
Yenan Chen,
Zhejiang University, CN

10:45 a.m.
Speaker:
Yenan Chen,
Zhejiang University, CN

11:10 a.m.
Speaker:
Jinfa Zhang,
Delta Electronics, CN

11:35 a.m.
Speaker:
Ilknur Colak,
Schneider Electric, DE

12:00 p.m.
Speaker:
Varajao Diogo,
Infineon Technologies

12:25 a.m. Lunch Break & Room Change

Afternoon Session

Poster Diologue Session

13:30 p.m-15:00 p.m | Hall 14 Poster Gallery

Poster Dialogue Session 1
Power Devices

Chairperson: Yijen Chan,
Cyntec Co., Ltd, TW, CN

Chairperson: Haihui Luo,
Zhuzhou CRRC Times Semiconductor, CN

01
A Simulation Investigation into HPD Power Modules
Lei Zhang, Chengdu Semi-Future Technology Co., Ltd., CN

02
900V high junction temperature and high reliability SiC MOSFET for Automotive Drive Applications
Xin Yuan, Zhuzhou CRRC Times Semiconductor Co., Ltd., CN

03
High power density 1700V/1000A RC IGBT module for Wind energy application
Hai Cai, Zhuzhou CRRC Times Semiconductor Co., Ltd., CN

04
A New 6 Inch IGCT Platform for up to 8.5 kV with Outstanding Current Capability
Christian Winter, Hitachi Energy Ltd. Semiconductors, CH

05
Robustness Assessment of Parallelly Operated 4.5kV/1500A IGBT Modules for HVDC Applications
Shota Saito, Mitsubishi Electric Corporation, JP

06
Research on Current Sharing and Optimization of Three-Chip Parallel IGBT Modules During Switching Process
Rui Li, Chengdu Semi-Future Technology Co., Ltd., CN

07
High-Temperature Design Considerations for Silicon Based Automotive Inverters with 750V EDT HiT
Nebojsha Levkovski, Infineon Technologies AG, DE

08
New-Generation 1400V U4 IGBT Module for Higher Power Density PV Inverter Applications
Hanwen Deng, Zhuzhou CRRC Times Semiconductor Co., Ltd., CN

09
8th Generation LV100 IGBT Module for High Power Central-type PCS
Bo Hu, Mitsubishi Electric & Electronics (Shanghai) Co., Ltd., CN

10
Beyond 4PP: Non-Contact Electrical Monitoring for Power Module Materials
Bo Chen, SURAGUS GmbH, CN

11
New Generation Low Inductance 6500V/600A Full SiC Power Module for Railway Traction Application
Guangyuan Qin, Zhuzhou CRRC Times Semiconductor Co., Ltd., CN

12
Design Considerations of Active Neutral Point Clamped Inverter for Energy Storage System
Andrew Yang, onsemi, CN

13
Performance Benchmarking of Si IGBT and SiC MOSFET in a 1200 V / 600 A Automotive EVD Power Module
Tommaso Stecconi, SwissSEM Technologies AG, CH

14
A Solid-State High-voltage High-frequency Pulse Power Supply with Adjustable Pulse Speed for Multi-Type Loads
Xin Li, Naval University of Engineering, CN

15
Effects of Gate Stress on Parameter Stability and Switching Losses in SiC MOSFETs
Wenqi Zhou, Bosch (China) Investment Ltd., CN

16
Impact of Threshold Voltage Mismatch, Layout Symmetry and External Gate Resistance on Current Sharing in Parallel SiC MOSFET in Half Bridges
Nima Lotfi, Nexperia Germany GmbH, DE

17
48 V GaN Motor Drive with Diode-Less Operation and Short 30 ns Dead Time for 70A/100kHz systems
Filippo Scrimizzi, Nexperia B.V., IT

18
Research on Packaging Structure of T-Type Three-Level GaN/SiC Hybrid Power Module
Yuhui Kang, Institute of Electrical Engineering, Chinese Academy of Sciences, CN

19
Optimization of Gate Driver Current Shaping to Enhance Switching Performance of SiC-MOSFETs
Lan Fang, Robert Bosch GmbH, CN

Poster Dialogue Session 2
Power Devices, Packaging and Reliability

Chairperson: Yong Kang,
Huazhong University of Science and Technology, CN

Chairperson: Wei Jing,
Semikron Danfoss, CN

20
Design Considerations for GDIC Slew-Rate Control: Voltage Peak Suppression and Temperature/Current-Driven Threshold Variation
Jaewon Choi, Infineon Korea, KR

21
Development of a New Package Supporting Both Through Hole and Surface Mount Types for Fan Applications
Masafumi Jochi, Mitsubishi Electric Corporation, JP

22
New automotive grade 1200 V SiC MOSFET-based Intelligent Power Module for auxiliary motor drive applications on BEV
Soo Hyuk Han, Infineon Technologies Korea Co., LLC, KR

23
Compact DIPIPM used in dual axles servo system
Siqing Lu, Mitsubishi Electric & Electronics (Shanghai) Co., Ltd., CN

24
Thermal correlation among junction, NTC, and heatsink in 1200 V automotive-grade CIPOS™ Maxi IPM for automotive auxiliary motor drives
Hyoungsub Jo, Infineon Technologies Korea, KR

25
Efficiency and Thermal Performance Comparison of SiC-MOSFET and Si-IGBT IPMs in the SPM31
Seonghyeon Kim, onsemi, KR

26
System-Level Short-Circuit Failure Mechanisms of IPMs in Practical Motor-Drive Applications
Yuquan Su, MiSiliconn Semiconductor Technologies Co., Ltd., CN

27
Junction Temperature Evolution of IGBTs under Power Cycling conditions
Juyoung Kim, onsemi, KR

28
Non-Destructive Bond Wire Failure Detection in SiC Power Transistors Using Reflectometry Signals
Valentyna Afanasenko, University of Stuttgart, DE

29
Advanced Thermal Management Solutions for Enhanced Compact 3D Power SiP Technologies
Po-An Lin, Advanced Semiconductor Engineering Inc, CN

30
Research on the Optimal Combination of Plasma Cleaning for Power Modules under Square Wave Voltage
Yuntian Gao, Xi'an Jiaotong University, CN

31
Reliability and Manufacturing Comparison of Flexible and Straight Pin Interconnects for Pin-Array Power Modules
Sven Matthias, SwissSEM Technologies AG, CH

32
Application of Laser Welding Technology in Power Module
Yi Chen, Advanced Semiconductor Engineering, INC, CN

33
Ceramic Packaging Technology for 250 ° C Medium High-Voltage Silicon Carbide Power Electronic Devices
Wenjie Wu, Xi'an Jiaotong University, CN

34
Thermal Characterization and Design Optimization of a Double Sided Cooled SiC Power Module for Automotive High Power Density Inverters
Alex Widhalm, Infineon Technologies AG, DE

35
Modeling Pressure Drop in Self-Circulating Phase-Change Cooling Systems for HVDC Converter Valves
Bendong Ma, Institute of Electrical Engineering, Chinese Academy of Sciences, University of Chinese Academy of Sciences, CN

36
Influence and Analysis of Different Device Modeling and Optimization on Tvj Calculation of SiC MOSFET under Extreme Operating Conditions
Hao Zhang, Infineon Technologies China Co. Ltd., CN

37
Effect of Humidity on the Reliability of Next-generation Chip Embedded PCB Packaging
Feng Li, China National Electric Apparatus Institute Co., Ltd., CN

38
A Newly 6-in-1 SiC Power Module Electro-Thermal-Reliability Co-Analysis
Feng Zhu, Beijing NEXIC Technology Co., Ltd, CN

39
Embedded SiC Technology in Power Electronics:Advances in Packaging, Manufacturing, and Reliability
Jinzhou Cao, Zhuzhou CRRC Times Electric UK Innovation Center, CN

40
Research and Development of a Low - Inductance, High - Power - Density Power Module Based on Transfer Molding Encapsulation Technology
Yuanjian Liu, ZHUZHOU CRRC TIMES semiconductor CO.,LTD, CN

41
An Overview of High Heat Capacitor Materials for eMobility Applications
Adel Bastawros, SABIC, USA

Poster Dialogue Session 3
Smart Grid and AI

Chairperson: Miao Zhu, Shanghai Jiao Tong University, CN

Chairperson: Teng Liu, China Southern Power Grid Electric Power Research Institute, CN

42
Application of Easy3B Module with new 7th Fast IGBT in String and Industrial & Commercial Energy Storage Systems
Kai Zhao, Infineon, CN

43
A Zero-Vector-Based DC Chopper Control Strategy for Current-Source Converter Wind Turbines to Enhance LVRT Capability
Junye Chen, Rostock University, CN

44
Reactive Power Support of AC Motor Loads under Low Voltage Ride-Through
Xin Qi, University of Science and Technology Beijing, CN

45
A Review of Global V2G Research from an Energy Technology Economics Perspective
Yueran Ni, Shanghai University of Engineering Science, CN

46
A Single-stage Portable Energy Storage System
Wenping Zhang, Infineon, CN

47
A Power Converter Hardware-in-the-Loop System for Energy-Domain AI Evaluation
Fan Zhang, Shenzhen Power Bell Technology Co., Ltd., CN

48
TD3-Based Current Control for Grid-Tied Inverters: Markov-State Design and Per-Unit Normalization
Licong Wu, Harbin Institute of Technology, CN

49
Analysis of Over-Current Withstand Capability of Discrete SiC MOSFETs for Interrupting MOV Paths in Solid-State Circuit Breakers
Wenqi Zhou, Bosch (China) Investment Ltd., CN

50
Coordinated network protection in DC grid
Yanzeng Wen, ASTRI Technology Research (Shenzhen) Co., Ltd., CN

51
A Solid-State Contactor for DC Electrical Power Systems
Yury Skorokhod, Transconverter, RU

Oral Session 15:00 p.m-16:40 p.m

Conference Room 14B

WBG Power Semiconductor Devices

Chair's opening speech
15:00 p.m.

Chairperson: Bo Zhang,
University of Electronic Science and Technology of China, CN

Chairperson: Masahiro Sasaki,
Fuji Electric Co., Ltd., JP

15:10 p.m.
Time-variant and Hysteresis Effects in the Thermal Characterization of Wide Band Gap Components
Gabor Farkas, Siemens DISW, HU

15:35 p.m.
All-SiC Power Modules Using 3rd-Gen Trench SiC MOSFETs with Expanded Current Ratings and SBD-Less Architecture
Song Chen, Fuji Electric (China) Co.,Ltd., CN

15:50 p.m.
Overload Investigation of 3.3kV SiC-MOSFET Power Module for Medium-Power Applications
Bochen Liu, Hitachi, CN

16:15 p.m.
New 6.5 kV IGBT Press-Pack Module and FRD for Multi-GW VSC- HVDC Applications
Evgeny Tsyplakov, Hitachi Energy Ltd., CH

Conference Room 14A

High Efficiency Power Converter

Chair's opening speech
15:00 p.m.

Chairperson: Min Chen,
Zhejiang University, CN

Chairperson: Teng Wu,
Schneider Electric, CN

15:10 p.m.
TLVR-Enhanced Interleaved Class-D Power Amplifier for High-Bandwidth Motor Emulation
Wei Cao, Harbin Institute of Technology, CN

15:35 p.m.
Development of A 3-level ANPC 800kW-class Power Stack based on 1200V IGBT Module for Renewable Energy Application
Zhengfeng Li, Mitsubishi Electric Corporation, JP

15:50 p.m.
A Three-Module Parallel Megahertz Inverter System with Wide Power Regulation Range
Xinyi Yan, Harbin Institute of Technology, CN

16:15 p.m.
5kW LLC Converter for ESS Based on GaN/SiC Devices
Wenping Zhang, Infineon, CN

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Thursday, August, 27, 2026 | Shenzhen World Exhibition and Convention Center, China | Conference Room 14

Morning Session

9:30 a.m. Conference Room 14B

Keynote 2

Semiconductor contribution to performance & efficiency of Automotive Traction Inverters

Speaker:
Mark Nils Muenzer,
Infineon Technologies AG, DE

Chairperson:
Gourab Majumdar,
Mitsubishi Electric Corporation, JP

10:10 a.m. Coffee Break & Room Change

Special Session 2 10:25 a.m-12:15 p.m

Conference Room 14B

AI in Power Electronics

Chair's opening speech
10:25 a.m.

Chairperson:
Jianing Wang,
Hefei University of Technology, CN

10:35 a.m.
Speaker:
Jianing Wang,
Hefei University of Technology, CN

11:00 a.m.
Speaker:
Yu Chen,
Huazhong University of Science and Technology, CN

11:25 a.m.
Speaker:
Weihao Hu,
University of Electronic Science and Technology of China, CN

11:50 a.m.
Speaker:
Ying Wu,
Hangzhou Zhuomai Intelligent Technology Co., Ltd., CN

Oral Session 10:25 a.m-12:15 p.m

Conference Room 14A

Advanced Power Semiconductor Devices Technology

Chair's opening speech
10:25 a.m

Chairperson: Norbert Pluschke,
CN-iCuTech, HKSAR, CN

Chairperson: Yi Tang,
Starpower Semiconductor, CN

10:35 a.m.
Next-Generation 2300 V IGBT Chipset for Renewable Energy Applications
Nick Schneider, SwissSEM Technologies AG, CH

11:00 a.m.
Performance of a New Power MOSFET Technology Designed to Serve the Requirements of Motor Drive Applications
Owen Song, Infineon Technologies, CN

11:25 a.m.
Low-Voltage p-GaN Gate HEMTs on 200-mm GaN-on-Si Platform with Record-Low RON, SP and RON × QG for Advanced AI Power Delivery
Yuhao Wang, Shenzhen Pinghu Laboratory, CN

11:50 a.m.
Temperature Dependent Characterization of the Dynamic RDS,on of Medium Voltage GaN Power HEMTs
Maximilian Goller, Chemnitz University of Technology, DE

12:25 a.m. Lunch Break

Afternoon Session

Poster Diologue Session

13:30 p.m-15:00 p.m | Hall 14 Poster Gallery

Poster Dialogue Session 4
High Performance Power Conversion

Chairperson: Lie Xu,
Tsinghua University, CN

01
Integrated Matrix Transformer with Loss Optimization for High-Efficiency & High-Power-Density Asymmetric Half-Bridge Resonant Converters
Xiaojun Liang, infineon, CN

02
Control of a GaN-Based T-Type Three-Level Converter
Tianyu Zhao, Institute of Electrical Engineering, Chinese Academy of Sciences, CN

03
Power Conversion Solutions for Next Generation 2000Vdc to 3000Vdc PV Inverter
Heng Wang, Infineon Integrated Circuit (Beijing) Co., Ltd., CN

04
DPWM-Based Synergetic Control for Wide-Range Three-Phase Voltage DC-Link Converters
Yushuo Pei, Hebei University of Technology, CN

05
Fast-Settling Dual-Loop 5 kV PSFB-CW HVDC Supply for Power Device Testing
Jing Tian, Institute of Electrical Engineering, Chinese Academy of Sciences; University of Chinese Academy of Sciences, CN

06
Current Balancing Control for Microsecond-Ranged Pulsed Current Generation in Laser Applications
Ziyi Xu, Hefei University of Technology, CN

07
Reduced-Order Piecewise Time-Domain Analysis of Symmetric LCL-DAB for Soft-Switching Boundary Analysis and Operating-Point Design
Kaiyin Mo, Huazhong University of Science and Technology, CN

08
Modeling and Optimal Control Strategy for LCC Resonant Converters Based on State Plane Analysis
Shuchen Yao, Huazhong University of Science and Technology, CN

09
Design and Development of a Low-Ripple,Low-Power High-Voltage Power Module for Spaceborne Transition Radiation Detector
Yalin Liu, Aerospace Information Research Institute, Chinese Academy of Sciences, CN

10
Design of a Hybrid EMI Filter for High-Voltage High-Power Mo-tor Drive Systems
Kun Ai, Institute of Electrical Engineering, Chinese Academy of Sciences, CN

11
A Control Method for Input Voltage Feedforward Using Secondary-Side PWM Waveforms in High Power Density Isolated DC-DC Brick Power Modules
Shilin Guo, HEFEI INSTITUTE OF TECHNOLOGY, CN

12
Magnetic self-alignment for high power wireless charging applications
Yanzeng Wen, ASTRI Technology Research (Shenzhen) Co., Ltd., CN

13
Metal Foreign Object Detection Method in Wireless Power Transfer Systems Based on circuit currents
Nikolay Kalugin, LLC Energet, RU

Poster Dialogue Session 5
Motor Drive & Motion Control

Chairperson: Jinsong Kang,
Tongji University, CN

Chairperson: Gaosheng Song,
Mitsubishi Electric & Electronics(Shanghai)Co., Ltd., CN

14
Fault-Tolerant Control for a Single Current Sensor Fault in Dual Three-Phase PMSM
Wenhao Lv, Harbin Institute of Technology, CN

15
A Low-parameter-sensitivity DPCC Algorithm Based On Reference Voltage Error Compensation
Jiaying Xu, North China University of Technology, CN

16
Open-winding PMSM drives with harmonic current suppression
Songhao Zhang, North China University of Technology, CN

17
Three-dimension Space Vector Pulse Width Modulation for Three-Phase Three-Level Series-End Winding Voltage Source Inverter
Zhixuan Luo, Tongji University, CN

18
Polyimide-Based Isolator with Ultra-High Withstand Voltage for Motor Drivers
Yong Wang, CrossChip MicroSystems, Inc., CN

19
Thrust Ripple Suppression of Symmetric Dual Three-Phase Linear Motors
Xinyue Li, TongJi University, CN

20
Research on Electromagnetic Transient Modeling Based on 12-Phase Synchronous Generator
Bowen Yu, TongJi University, CN

21
Speed-Dependent Electromagnetic－Thermal Analysis of LSLSM Mover
Lin Fan, Tongji University, CN

22
A Power Pulsations Control Design based on Digital Motor Control Processing Tehniques DSP
Nicușor Totor, CFR, RO

23
Deadbeat Direct Speed Control for IPMSM Based on Extended State Observer
Jinyang Cai, Harbin Institute of Technology, CN

24
Research on Online Apparent Inductance Identification Method for PMSMs Based on dq-Axis Coupling Suppression
Rui He, Harbin Institute of Technology, CN

25
MLP-PI Current Control Strategy for PMSM Considering Inverter Nonlinearity
Jinlong Li, infineon, CN

26
Modeling of Permanent Magnet Synchronous Motors Based on Physics-Informed Neural Network
Liangrong Sun, Tongji University, CN

27
High Performance Sensorless Control of Permanent Magnet Synchronous Motor under Low Carrier Ratio
Kaixin Gao, Harbin Institute of Technology, CN

28
Parameter Adaptive Deadbeat Control for Permanent Magnet Linear Synchronous Motors
Zhiyu Zhang, Harbin Institute of Technology, CN

29
A Deadbeat Predictive Control Strategy Based on Parameter Tuning
Shan Wang, Harbin Institute of Technology, CN

30
Fixed-Time Consensus-Based Cooperative Speed Control for Multi-PMSM Systems with Optimal Current Regulation
Zhexi Xu, Harbin Institute of Technology, CN

Poster Dialogue Session 6
Automotive Power Electronics and Electrified Transportation

Chairperson: Guoqiang Zhang,
Harbin Institute of Technology, CN

Chairperson: Gang Yao, Shanghai Maritime University, CN

31
A Four-Stage Model Predictive Current Control for PMSM Based on Voltage Vector Action Mode Reconstruction
Weihe Jing, North China University of Technology, CN

32
Model Predictive Pulse Shifting Control Method for Permanent Magnet Synchronous Motor Based on SHEPWM
Xilin Jin, North China University of Technology, CN

33
Model Predictive Current Control of PMSM Based on Bayesian Recursive Least Squares
Bing Song, North China University of Technology, CN

34
Novel observer for permanent magnet synchronous motor drive systems
Ge Gao, North China University of Technology, CN

35
Fault-Tolerant Model Predictive Current Control of Dual Three-Phase PMSM Based on Virtual Vectors
Xi Rao, Tongji University, CN

36
The Information Network Arhitecture and Intelligent Motor Processing
Nicușor Totor, totor pfa, RO

37
Deadbeat Current Harmonic Suppression Optimization Strategy Based on Rotating Coordinate Frame
Shan Wang, Harbin Institute of Technology, CN

38
New Generation Automotive-Grade 1500V SiC MOSFET devices for Applications with 950V bus voltage
Wei Liu, Zhuzhou CRRC Times semiconductor Co., LTD., CN

39
Enhancing Short-Circuit Evaluation of Automotive SiC MOSFET Power Modules: An Advanced Industry Approach
Jiani He, Bosch (China) Investment Ltd., CN

40
Advanced Isolated Gate Driver IC for High-Power-Density SiC/Si Power Modules in xEV Applications
Habu Yo, MITSUBISHI ELECTRIC CORPORATION, JP

41
Optimized Multi-Degree-of-Freedom Modulation for a 6.6 kW Integrated OBC－LDC Charger for Electric Vehicles
Chenli Zhou, Southwest Jiaotong University, CN

42
A Low-Loss Modulation Strategy for Dual Active Resonant Converters
Hongze Bu, China Electronic Product Reliability and Environmental Test Institute, CN

43
Heterogeneous Test Bench Concept for Grid-Constrained Fast DC Charging
Nikolay Volskiy, Charge Evolution, RU

Oral Session 15:00 p.m-16:40 p.m

Conference Room 14B

AI in Power Electronics

Chair's opening speech
15:00 p.m.

Chairperson: Jinjun Liu,
Xi´an Jiaotong University, CN

Chairperson: Lifeng Chen,
Infineon Technologies, CN

15:10 p.m.
Topology-Aware Attention-Enhanced Heterogeneous Graph Convolution for MMC Fault Diagnosis
Zhangtiancheng Wen, Shanghai Maritime University, CN

15:35 p.m.
A Novel Reinforcement Learning-based Controller for DC-DC Buck Converter
Chaohong Zhang, Southeast University, CN

15:50 p.m.
A Robust PPO-based Control Scheme for 1 MHz DC-DC Converters with Multi-Domain Disturbance Resilience
Chuanchuan Liang, Southeast University, CN

16:15 p.m.
Lightweight Arc Fault Detection by Optimized Machine Learning with Multi-dimensional Features
Yanzeng Wen, ASTRI Technology Research (Shenzhen) Co., Ltd., CN

Conference Room 14A

Packaging and Reliability for Power Semiconductors

Chair's opening speech
15:00 p.m.

Chairperson: Naoto Fujishima,
Fuji Electric, JP

Chairperson: Xuhui Wen,
Institute of Electrical Engineering, Chinese Academy of Sciences, CN

15:10 p.m.
New Pressure Technology for SiC Power Modules
Norbert Pluschke, CN-iCuTech Semiconductor Co.Ltd HongKong, HKSAR, CN

15:35 p.m.
Application of Sintering Technology in SiC Modules
Shaolun Yang, Advanced Semiconductor Engineering, Inc. (ASE), CN

15:50 p.m.
Power cycling and thermal shock reliability of novel copper preforms
Sri Krishna Bhogaraju, CuNex GmbH, DE

16:15 p.m.
A Dual-Symmetric S-Channel Composite Heatsink for High-Reliability PEBB Modules
Jiahao Zheng, Zhejiang University, CN

Conference

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Friday, August, 28, 2026 | Shenzhen World Exhibition and Convention Center, China | Conference Room 14

Morning Session

9:30 a.m. Conference Room 14B

Keynote 3

TBD

Speaker:
Junsheng Wei,
BYD Company Limited, CN

9:30 a.m. Conference Room 14B

Keynote 4

Enabling the Medium-Voltage Revolution: Innovations in 10kV SiC Power Packaging Platforms

Speaker:
Ziyang Gao,
Hong Kong Microelectronics Research and Development Institute, HKSAR, CN

Chairperson:
Dong Li,
Infineon Technologies Asia Pacific Pte Ltd, SG

Oral Session 10:25 a.m-12:40 p.m

Conference Room 14B

Motor Drives and Electrified Transportation

Chair's opening speech
10:25 a.m.

Chairperson: Yongdong Li,
Tsinghua University, CN

Chairperson: Dapeng Zheng,
Shenzhen Hopewind Electric, CN

10:35 a.m.
DCVO-ESO Fusion for High-Precision Position Estimation in Sensorless PMSM Drives
Linna Ji, Harbin Institute of Technology, CN

11:00 a.m.
Analysis of Two In-Phase Current Sensing Implementations for Humanoid Robotic Motor Control
Alan Lun Wai-Keung, Infineon Technologies Hong Kong Ltd., HKSAR, CN

11:25 a.m.
A Novel CMV and ZSC Simultaneous Suppression Method for Open-Winding PMSM with Common DC Bus Based on DPCC
Bowen Wang, North China University of Technology, CN

11:50 a.m.
SiC Power Module for xEV with High Power-Density, Low Stray-Inductance, and Optimized Chip Paralleling Design
Yuhang Yang, Hangzhou Silan Microelectronics Co., Ltd. CN

Conference Room 14A

Power Electronics for Smart Grid

Chair's opening speech
10:25 a.m.

Chairperson: Meiqin Mao,
Hefei University of Technology, CN

Chairperson: Jianping Ying,
Delta Electronics, CN

10:35 a.m.
Proper Design of Energy-Supporting for Sustainable Li-ion Battery Performance in Electric Vehicles
Christos Mademlis, ARISTOTLE UNIVERSITY OF THESSALONIKI, GR

11:00 a.m.
Simplified Modeling and Analysis of Multi-Phase COT Buck Converter with Overlapping Operation based on Pade Approximation
Na Yan, Institute of Microelectronics of the Chinese Academy of Sciences, CN

11:25 a.m.
Power Path Reconfiguration of a Three-Port Converter for Short-Term Overload
Peng Yang, Huazhong University of Science and Technology, CN

11:50 a.m.
Coordinated and Market-Oriented Virtual Power Plants for Enhancing Building Energy Performance
Christos Mademlis, ARISTOTLE UNIVERSITY OF THESSALONIKI, GR

12:40 p.m. Lunch Break

13:30 p.m. The PCIM Asia Shenzhen Tour